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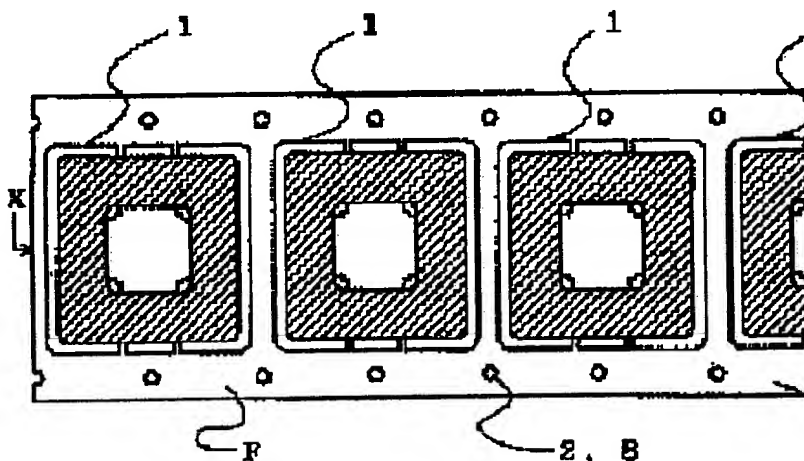
**(54) METAL PLATE WITH
ADHESIVE TAPE FOR
SEMICONDUCTOR
DEVICE AND
MANUFACTURE
THEREOF**

(57) Abstract:

(a)

PROBLEM TO BE SOLVED: To stick an adhesive layer with high accuracy, while easily peeling a release tape on the adhesive layer by selectively bringing only the adhesive layer in a region abutted against a previously predetermined bonded region in a metal plate to the state, in which the adhesive layer is bonded with the metal plate.

SOLUTION: The laminated strip of a copper strip 11 and an adhesive pate 3 which is forwarded from a hot press device is cut at every four heat sinks, and metal frames F with the adhesive tapes are manufactured. The release tape 4 is peeled in a sticking process to the semiconductor device in the metal frame F with the adhesive tape. Only



(b)

